IN THE CLAIMS

Without prejudice or disclaimer, please amend claims 3, 4 and 5 to read as shown below:

1. (Original) A method for manufacturing a biaxially textured pure metal or alloy layer deposited by electroplating process on the surface of a pure metal or alloy substrate having *single-crystalline or quasi-single-crystalline orientation*, the biaxially textured pure metal or alloy layer being deposited on the surface of the pure metal or alloy substrate having single-crystalline orientation or quasi-single-crystalline orientation using electroplating process such as a direct current electroplating process (DC process), a pulse current electroplating process (PC process) or a periodic reverse current plating process (PR process).

2. (Original) The method for manufacturing a biaxially textured pure metal or alloy layer deposited by electroplating process on the surface of a pure metal or alloy substrate having single-crystalline orientation or quasi-single-crystalline orientation according to claim 1, wherein the biaxially textured pure metal or alloy layer is electroplated in a plating solution comprising 100~400g/l nickel sulfate, 0~70g/l nickel chloride, 20~80g/l boric acid, 0~50g/l sodium sulfate, 0~10g/l sodium

tungstate and 0~10g/l cobalt chloride at pH 1.5~7 and 50~80°C.

3. (Currently Amended) The method for manufacturing a biaxially textured pure metal or alloy layer deposited by electroplating process on the surface of a pure metal or alloy substrate having single-crystalline or quasi-single-crystalline orientation according to claim 1 ~~or 2~~, wherein the biaxially textured pure metal or alloy layer is deposited in the plating solution at a cathode current density of 3~20A/dm^2 using a direct current electroplating process (DC process), the deposited pure metal or alloy layer having a texture fraction (TF) of 0.97 or more on the (001) plane.

4. (Currently Amended) The method for manufacturing a biaxially textured pure metal or alloy layer deposited by electroplating process on the surface of a pure metal or alloy substrate having single-crystalline orientation or similar orientation according to claim 1 ~~or 2~~, wherein the biaxially textured pure metal or alloy layer is deposited in the plating solution under conditions of a cathode current density of 3~20A/dm^2, a cathode current time of 1~100msec and a down time of 1~100msec using a pulse current electroplating process (PC process), the deposited pure metal or alloy layer having a

texture fraction (TF) of 0.97 or more on the (001) plane.

5. (Currently Amended) The method for manufacturing a biaxially textured pure metal or alloy layer deposited by electroplating process on the surface of a pure metal or alloy substrate having single-crystalline orientation or similar orientation according to claim 1 ~~or 2~~, wherein the biaxially textured pure metal or alloy layer is deposited in the plating solution under conditions of a cathode current density of 3~20A/dm^2, a cathode current time of 1~100msec and an anode current time of 1~100msec using a periodic reverse current plating process (PR process), the deposited pure metal or alloy layer having a texture fraction (TF) of 0.97 or more on the (001) plane.

6. (Original) A biaxially textured pure metal or alloy layer deposited by electroplating process on the surface of a pure metal or alloy substrate having single-crystalline orientation or similar orientation.

7. (Original) The biaxially textured pure metal or alloy layer deposited by electroplating process on the surface of a pure metal or alloy substrate having single-crystalline

orientation or similar orientation according to claim 6, wherein the biaxially textured pure metal or alloy layer is a cubic crystal texture having a misorientation on the c-axis of 8° or less and a misorientation on the plane formed by the a-axis and b-axis of 15° or less in which the misorientation on the c-axis is determined by a Full Width at Half Maximum of peaks on the θ-rocking curve and the misorientation on the plane formed by the a-axis and b-axis is determined by a Full Width at Half Maximum of peaks on the Φ-scan.